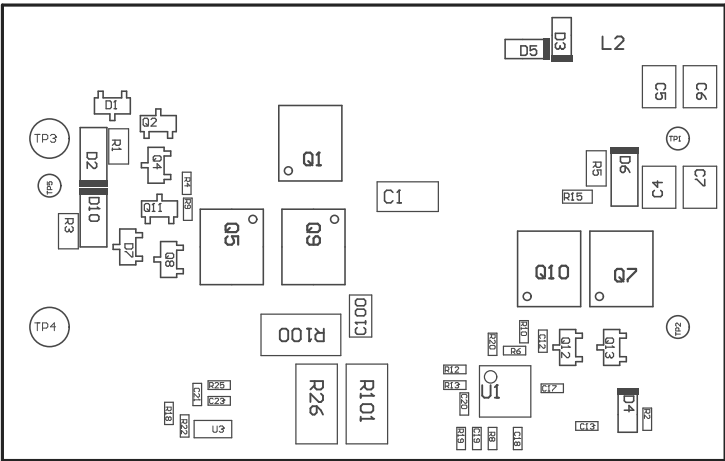


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP8861	REV: C	SVN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 5/30/2016 2:21:54 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP8861	REV: C	SVN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 5/30/2016 2:21:55 PM		TEXAS INSTRUMENTS

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